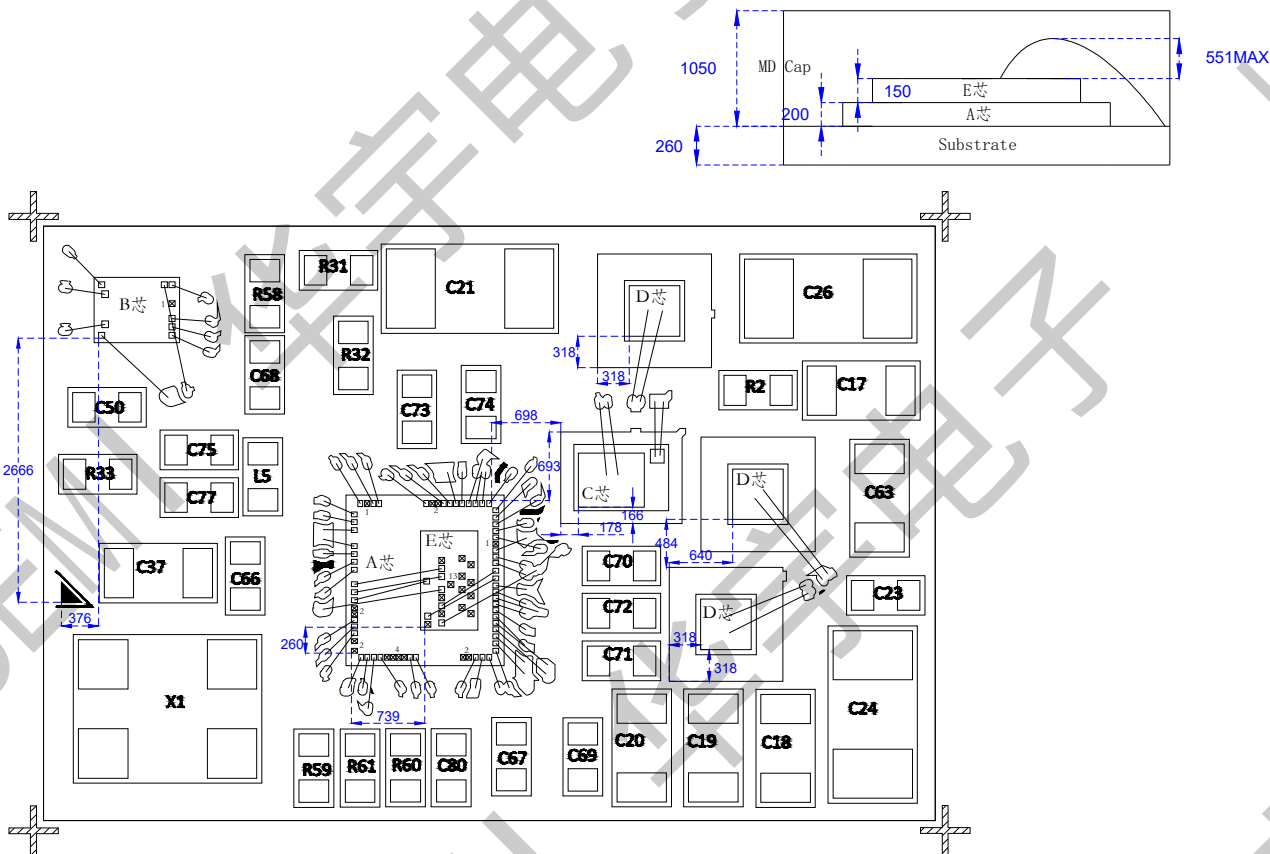
 池州华宇电子科技股份有限公司 CHI ZHOU HISEMI ELECTRONICS TECHNOLOGY CO.,LTD 焊线图纸 Bonding Diagram				客户代码 Customer No.	线图号 Drawing No.	封装外型 PKG Type	LGA56L(6X9X1.31-P0.5)
焊线种类 Wire Type	焊线直径(μm) Wire Diameter	焊线根数 NO. of wire	焊线总长(μm) Total wire length	最长线长(μm) Longest wire length	最短线长(μm) Shortest wire length	塑封料型号(绿色环保) Compound Type (Green)	基板编码 Substrate No.
镀钎铜丝 PdCu	20			1215	314	首选(Preferred): G760L TypeA 备选(Optional):	
剪刀型号 Capillary Type			客户图号 Customer drawing NO.				



框架传送方向(装片): L/F Direction (D/A):	实物图: Chip photo:	特殊说明 Special Instructions: DB注意: 装片位置公差为±35μm; WB注意: 数字为不打线PAD个数。
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说明 Instructions	粘片胶类型 epoxy type	芯片名称 Die name	芯片尺寸 Die Size	最小焊盘尺寸 Min BPP(μm ²)	最小焊盘间距 Min BPP(μm)	铝垫厚度(μm) Pad Thickness	焊盘下是否有电路 Circuit under Pad	划片道宽度 Street line (μm)	晶圆尺寸 Wafer Size	是否是 Low-K If low-k?	减薄厚度 (μm) Wafer Thickness
A芯: DIE A	绝缘胶 (Non-conductive) 2025DSI		1722X1596(μm ²) 67.79*62.83(mil ²)	59.4*48.6	56.7	1.45	是/Yes	62	12	是/Yes (55nm)	200
B芯: DIE B	绝缘胶 (Non-conductive) 2025DSI		660X860(μm ²) 25.98*33.86(mil ²)	60*60	80	1.2	是/Yes	60	8	否/NO	170
C芯: DIE C	导电胶 (conductive) 84-1L.MISR4		958X668(μm ²) 37.72*26.29(mil ²)	138*138	463	NA	否/No	60	8	否/NO	160
D芯: DIE D	导电胶 (conductive) 84-1L.MISR4		610X610(μm ²) 24.02*24.02(mil ²)	510*510	NA	4.0	否/No	100	6	否/NO	200
E芯: DIE E	绝缘胶 (DAF) (Non-conductive) HR-5104		641.07X1061.84(μm ²) 25.24*41.80(mil ²)	60.3*60.3	81	2.8	是/Yes	60	12	是/Yes (55nm)	150

制图日期 Create Date	生效日期 Effective Date	客户确认签字/盖章: Customer Signature
拟制 Prepared by	审核 Checked by	批准 Approved by

*温馨提示: 图纸为产品下线生产的唯一依据, 请您认真确认, 我司依据您回签后的图纸生产, 如图纸错误会产生不可估量损失, 谢谢!
 *warm tips: the drawing is the only basis for the production of the product. Please confirm it carefully. Our company will produce the drawings according to the drawings you have signed back, such as drawing mistakes, which will produce incalculable loss. Thank you